

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	203	(passive near3 device or smd or resistor or capacitor or diode) near10 (noflow or no-flow or reflow or preform or preformed or strip) near3 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 08:39
L2	422	surface near mount near capacitor	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/11 08:54
L4	156	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer or substrate) same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 09:24
L5	400	(chip or die) adj capacitor same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 09:35
L6	203	(passive near3 device or smd or resistor or capacitor or diode) near10 (noflow or no-flow or reflow or preform or preformed or strip) near3 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 09:53
L7	73	surface near mount near capacitor same (encapsulant or encapsulation or encapsulating or resin or epoxy or underfill or underfilling or under-fill or molding or adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 10:07

## EAST Search History

L8	156	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer or substrate) same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 10:23
L9	292	(surface near mount\$2 or chip or mounted or mounting or decoupling or smt or smd) near2 (capacitor or resistor or diode or inductor) and (chip or die or ic) near4 (underfill\$3 or under-fill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 10:33
L10	95	((two-terminal or two adj terminal or dogbone) near2 (capacitor or resistor or device or smd or smt or surface near mount or flip near chip)) same (solder\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 10:51
L11	273	257/747.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 10:58
L12	446	257/789.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 11:19
L13	475	257/793.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 11:51
L14	316	257/795.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 12:58
L15	129	257/737,738,747,778,783,789,793,795.ccls. and (two near terminal or two-terminal or dogbone or dog-bone)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 13:23

## EAST Search History

L16	170	257/737,738,747,778,783,789,793,795.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt) near6 (solder\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 14:21
L17	1240	257/E23.119.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 13:50
L18	34	257/E23.123.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 14:05
L19	155	257/E23.133.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 14:05
L20	2	257/E23.119.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt) near6 (solder\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 14:22
L21	144	257/E23.119.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 14:22

# Interference Search

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L22	0	((passive or dogbone or resistor or capacitor) near3 (surface near mount\$3) or smd or smt) near15 (underfill\$4 or under adj fill\$4)).clm.	US-PGPUB	OR	ON	2006/07/11 14:58
L23	1	((capacitor) near15 (underfill\$4 or under adj fill\$4)).clm.	US-PGPUB	OR	ON	2006/07/11 14:58
L24	27	((passive or dogbone or resistor or capacitor) near3 (surface near mount\$3) or smd or smt) near15 (resin or epoxy or encapsulat\$4 or encapsulant)).clm.	US-PGPUB	OR	ON	2006/07/11 15:22
L25	16	((encapsulant or encapsulat\$4 or underfill\$4 or under adj fill\$4 or molding) near4 (fillet or filleted)).clm.	US-PGPUB	OR	ON	2006/07/11 15:26
L26	87	((capacitor or passive or chip or smd or smt or surface near mount or surface near mounted or resistor) near8 ((two or dual or end) near2 (electrode or terminal or contact) or dogbone\$3) and (encapsulant or encapsulat\$4 or underfill\$4 or under adj fill\$4 or molding)).clm.	US-PGPUB	OR	ON	2006/07/11 15:27